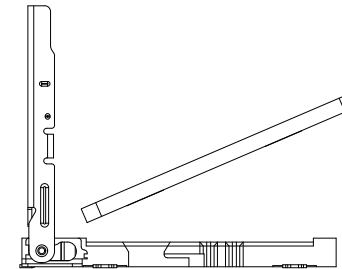
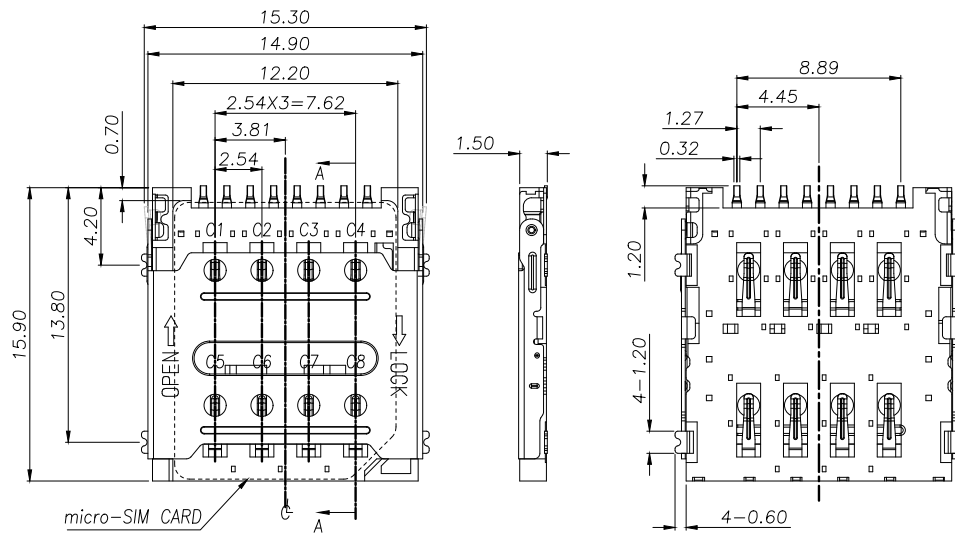
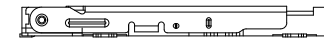


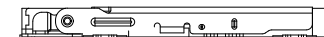
RoHS Compliant



STEP 1 INSERT Micro-SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH

NOTES:

1. ELECTRICAL CHARACTERISTICS

1-1. CONTACT RESISTANCE: 60 Milliohms Max

1-2. INSULATION RESISTANCE: 1,000 Megohms Min.

1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.

2. MECHANICAL CHARACTERISTICS

2-1. OPERATION TEMPERATURE RANGE: -25°C~+70°C

2-2. DURABILITY: 5000 CYCLES

3. MATERIAL:

3-1. HOUSING: THERMOPLASTIC,UL 94-V0

3-2. TERMINAL: PHOSPHOR BRONZE,T=0.15

3-3. SHELL: STAINLESS STEEL,T=0.15

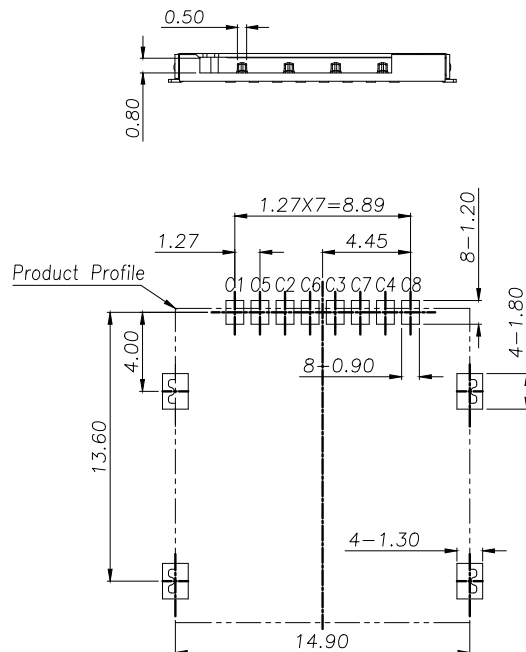
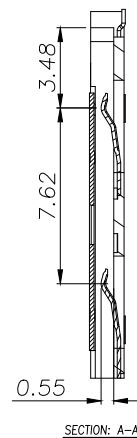
4. FINISHED:

4-1. TERMINAL: Ni PLATED UNDER,Au PLATED ON

CONTACT AREA,G/F PLATED ON SOLDERTAIL

4-2. SHELL: Ni PLATED UNDER,G/F PLATED ON SOLDERTAIL

SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	RESERVED
C5	GND
C6	VPP
C7	I/O
C8	RESERVED



RECOMMENDED PCB LAYOUT
GENERAY TOLERANCE ± 0.05

深圳市敏连达科技有限公司 Shenzhen Minlianda Technology Co.,Ltd.		品名(ITEM NO)	MICRO SIM 8P 掀盖1.5H		
		料号(PART NO)	MLD-MICRO XG-8P-H1.5		
单位(UNIT): MM	未注公差 TOLERANCE UNSPECIFIED	版次(REV): A/O	页次(PAGE):1/1	设计 (DESIGN)	柯南
比例(SCALE) 1:1	X.X ± 0.38 X.XX ± 0.20 X.XXX ± 0.10 X" ± 5 X.X" ± 2	模号 (MODEL NO)	图号 (DWG NO)	审核 (CHECKED)	邱敏
				核准 (APPROVED)	陈镇
		图号 (DWG NO)	MLD-2509031032	核准 (APPROVED)	陈镇